



UPDATE CHANGE NOTIFICATION
Generic Copy

20-Mar-2007

SUBJECT: ON Semiconductor Update Notification #15750

TITLE: Retraction of devices listed on UN 15734

PROPOSED FIRST SHIP DATE: 20 Mar 2007

AFFECTED CHANGE CATEGORY(S): ON Semiconductor Assembly

AFFECTED PRODUCT DIVISION(S): All

ADDITIONAL RELIABILITY DATA: N/A

SAMPLES: N/A

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:

Contact your local ON Semiconductor Sales Office or Scott Brow<Scott.Brow@onsemi.com>

NOTIFICATION TYPE:

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact your local ON Semiconductor Sales Office.

DESCRIPTION AND PURPOSE:

This notice is to retract specific VHVIC devices listed below that were include on Update Notification #15734 issued on Feb 26 2007. The purpose of the original PCN was to notify customers that ON Semiconductor is qualifying a new BOM with a different lead frame, die attach epoxy, and mold compound, to improve the moisture sensitivity level (MSL) for the SOT223 package. This BOM change will not occur on VHVIC devices. We apologize for any concern this may have caused.



Update Notification #15750

AFFECTED DEVICE LIST

NCP1010ST100T3G
NCP1011ST100T3G
NCP1011ST65T3G
NCP1012ST130T3G
NCP1012ST65T3G
NCP1013ST100T3G
NCP1013ST130T3G
NCP1013ST65T3G
NCP1014ST100T3G
NCP1014ST65T3G
NCP1052ST136T3G
NCP1052ST44T3G
NCP1053ST136T3G
NCP1053ST44T3G
NCP1054ST136T3G
NCP1055ST136T3G
NCP1055ST44T3G